

MATERIAL DECLARATION SHEET



Material Number	CR0603-LF			
Product Line	Chip Resistor			
Compliance Date	04/01/2003			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	0.00166	Aluminum oxide	1344-28-1	96%	82.4928%	85.93%
				Silicon dioxide	14808-60-7	4%	3.4372%	
2	Conductor Layer	Conductor glass	0.00004	Silver	7440-22-4	96%	2.1945%	2.31%
				Bismuth trioxide	1304-76-3	1%	0.028875%	
				Barium oxide	1304-28-5	1%	0.028875%	
				Silicon dioxide	7631-86-9	1%	0.028875%	
				Boron oxide	1303-86-2	1%	0.028875%	
3	Resistive Element	Resistor glass	0.000025	Ruthenium dioxide	12036-10-1	25%	0.33%	1.32%
				Silver	7440-22-4	40%	0.528%	
				Palladium	7440-05-3	15%	0.198%	
				Lead oxide glass	1317-36-8	20%	0.264%	
4	Over Coating	Epoxy	0.00003	Epoxy	29690-82-2	100%	1.57%	1.57%
5	Marking	Marking ink	0.000003	Epoxy	25068-38-6	100%	0.16%	0.16%
6	End Terminal	NI-CR	0.0000025	Nickel	7440-02-0	80%	0.104%	0.13%
				Chromium III	7440-47-3	20%	0.026%	
7	Ni Plating	Nickel	0.00009	Nickel	7440-02-0	100%	4.54%	4.54%
8	Sn Plating	Tin	0.00008	Tin	7440-31-5	100%	4.04%	4.04%
		Total weight	0.0019305					

MATERIAL DECLARATION SHEET

BOURNS[®]

This Document was updated on: 05.18.2010

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS exemption 5 – lead in glass of ... electronic components...